

US00D519470S

(12) United States Design Patent (10) Patent No.:

Hahn et al.

US D519,470 S

** Apr. 25, 2006 (45) Date of Patent:

MODULAR ELECTRONIC HOUSING AND **ASSEMBLIES**

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14 Years (**) Term:

Appl. No.: 29/233,206

Filed: Jun. 28, 2005 (22)

Related U.S. Application Data

| (62) | Division of application No. 2 | 29/195,922, | filed or | n Dec. 8 | 8, |
|------|-------------------------------|-------------|----------|----------|----|
| | 2003, now Pat. No. Des. 499,5 | | | | |

| (| (51) | LOC (8) Cl. | 13-03 |
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(52)

(58)D14/240; 174/50, 52.1; 220/4.02; 361/600, 361/601, 679, 688, 704, 724, 796 See application file for complete search history.

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(57)**CLAIM**

The ornamental design for a modular electronic housing and assemblies, as shown and described.

DESCRIPTION

The modular electronic housing and assemblies comprises a modular electronic housing intended to be used to house electronic circuit boards and their included electronic components.

The FIGURE is a right side perspective view of a modular electronic housing and assemblies showing our new design.

The broken line disclosure in the drawings are for illustrative purposes only and form no part of the claimed design.

1 Claim, 1 Drawing Sheet



